

The logo for SICE (Semiconductor and Integrated Circuit Industry Innovation Exhibition) is displayed in a stylized, white, italicized font against a dark blue background with circuit-like patterns.

# 2026杭州国际 半导体与集成电路产业创新展览会

Hangzhou International Semiconductor and Integrated Circuit Industry Innovation Exhibition 2026

**同期举办：长三角集成电路产业协同创新发展大会**

Yangtze River Delta Integrated Circuit Industry Collaborative Innovation and Development Conference

**2026.05.14-16**

**杭州大会展中心-浙江**

Hangzhou Grand Convention and Exhibition Center-Zhejiang

## 批准单位 / Approved by

中华人民共和国商务部  
Ministry of Commerce of the  
People's Republic of China

## 主办单位 / Hosted by

浙江省半导体行业协会  
Zhejiang Semiconductor  
Industry Association

上海高登会展集团有限公司  
Golden Conference & Exhibition Group

## 协办单位 / Co-organized by

中国国际科技促进会半导体产业发展分会  
Development of Semiconductor Industrial Branch, CIAPST

## 承办单位 / Organized by

上海大道国服展览有限公司  
Shanghai Supervip Exhibition Co., Ltd.

[www.sicexpo.cn](http://www.sicexpo.cn)

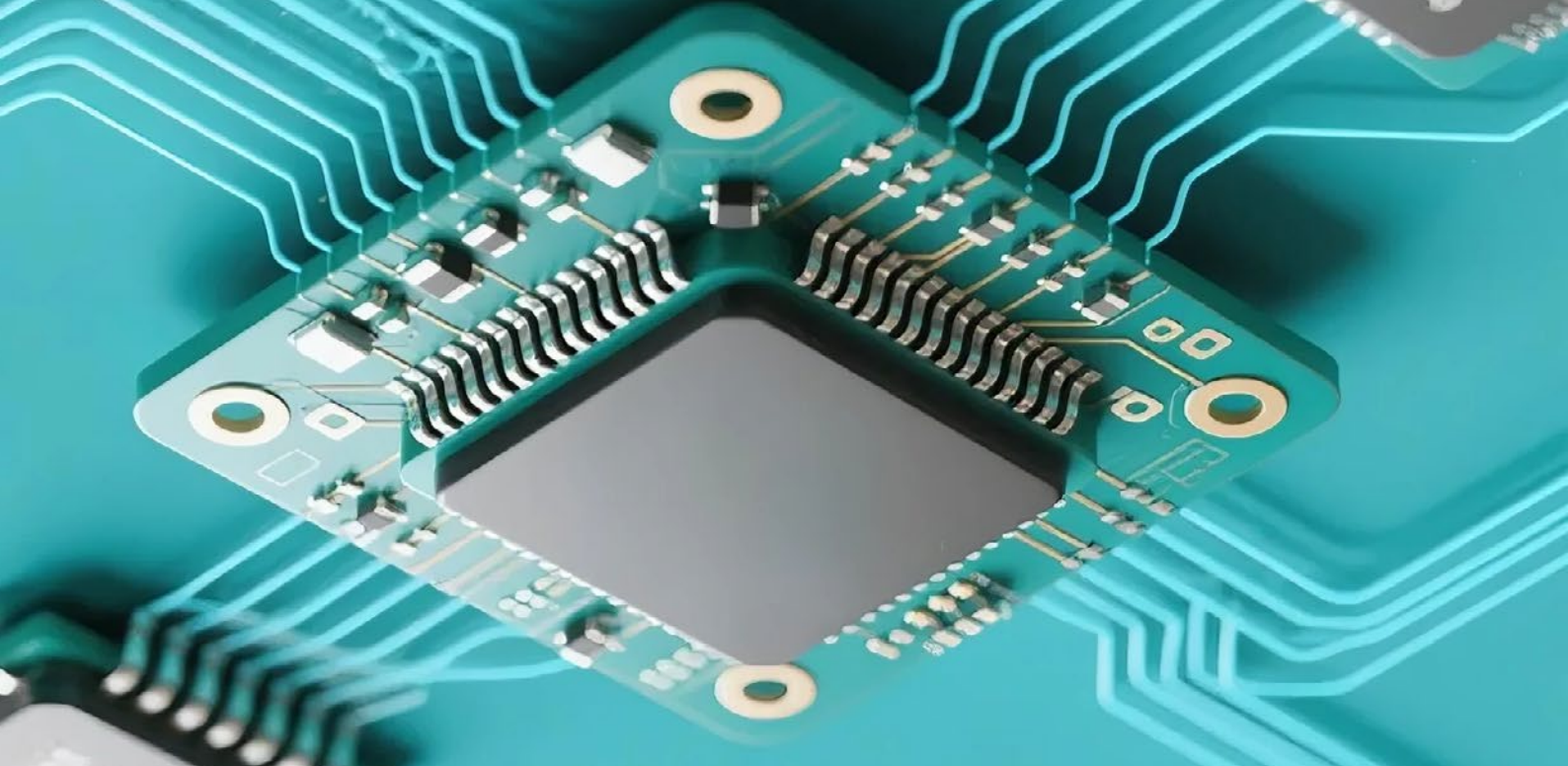


## 展会介绍 EXHIBITION BACKGROUND

半导体与集成电路产业是代表未来的重要引擎性、支撑性、标志性蓝海产业。随着全球数字化转型的加速，半导体与集成电路产业的重要性日益凸显，浙江省半导体与集成电路产业现已建立起涵盖设计、制造、封装测试、装备及零部件、材料等环节的完整产业链，形成了以杭、甬、绍、嘉为核心的环杭州湾模拟芯片与功率器件特色产业集群和以湖、金、衢、丽为核心的半导体材料支撑产业集群。作为国家集成电路产业设计的重要基地，杭州市政府高度重视集成电路产业的发展，先后出台了《杭州市进一步鼓励集成电路产业加快发展的专项政策》《关于促进集成电路产业高质量发展的实施意见》以及《关于推动经济高质量发展的若干政策》，在企业研发补贴、税收优惠、人才引进和平台建设等方面予以资金支持，提出打造长三角集成电路产业核心城市，会同宁波市、绍兴市、嘉兴市协同打造环杭州湾集成电路核心产业集聚区。2024年，杭州集成电路产业规模突破1000亿元大关，设计业实力稳居国内第一梯队；在产业生态建设方面，杭州构建起覆盖“芯片设计-集成电路制造-关键材料和设备-规模化应用”的完整产业链，集聚上下游产业超400家，在特色芯片设计、化合物半导体、半导体核心材料、关键设备及零部件等领域培育一批上市企业和国家级专精特新“小巨人”企业，产品广泛服务于消费电子、工业控制、汽车电子、人工智能等多个领域，为行业发展提供了重要力量。

The semiconductor and integrated circuit (IC) industry will be a blue ocean market that serves as an engine, foundation, and hallmark of the future. With the acceleration of global digital transformation, it is of great significance for the semiconductor and IC industry. Zhejiang has established a complete industrial chain covering design, manufacturing, packaging and testing, equipment and components, and materials. It has also developed two distinctive industrial clusters, one is the Hangzhou Bay Rim cluster specializing in analog chips and power devices with its core in Hangzhou, Ningbo, Shaoxing, and Jiaying, and the other is the semiconductor materials support cluster centered in Huzhou, Jinhua, Quzhou, and Lishui. As a key national base for integrated circuit design in China, the Hangzhou Municipal Government places great emphasis on the development of the IC. It has successively introduced a series of special policies, including the "Special Policies for Further Encouraging the Accelerated Development of the IC Industry in Hangzhou", "Implementation Opinions on Promoting the High-Quality Development of the IC Industry", and "Policies on Promoting High-Quality Economic Development", providing comprehensive funding support in areas such as enterprise R&D subsidies, tax incentives, talent recruitment, and platform construction. The city has proposed to build itself into a core hub for the integrated circuit industry in the Yangtze River Delta region, while collaborating with Ningbo, Shaoxing, and Jiaying to jointly create a key integrated circuit industrial cluster in the Hangzhou Bay area. In 2024, Hangzhou's integrated circuit industry scale exceeded the 100 billion yuan, while its design sector consistently ranks among China's forefront. In terms of the development of industrial ecosystem, Hangzhou has established a fully integrated industrial chain covering chip design, integrated circuit manufacturing, key materials and equipment, and large-scale application. The city has attracted over 400 upstream and downstream enterprises and cultivated a group of listed companies and national-level "Little Giant" enterprises specializing in niche chip design, compound semiconductors, core semiconductor materials, and critical equipment and components. These products serve a wide range of sectors, including consumer electronics, industrial control, automotive electronics, and artificial intelligence, which contributed to the industry's advancement.

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## 新的机遇 NEW OPPORTUNITIES

为给更多的半导体与集成电路企业搭建一个集产品展示、贸易洽谈、技术交流、投资合作于一体的国际化平台。在上级主管部门的指导下，高登会展联合相关主管单位将于2026年05月14日-16日在杭州大会展中心召开“2026杭州国际半导体与集成电路产业创新展览会”（简称：长芯展）。展会以“链接芯生态，智造新机遇”为主题，展会总规划面积为3万平米，展品范围涵盖关键设备及零部件、半导体材料、EDA&IP、集成电路设计、制造、封装测试、半导体服务、芯片应用等产品和技術。本届展会将汇聚全球半导体与集成电路行业尖端技术、前沿产品，从芯片设计到集成电路解决方案，全方位展示半导体与集成电路产业的创新力量。通过展览与论坛相结合形式，从不同视角全方位展示中国（尤其是长三角地区）半导体与集成电路产业的创新实力与发展成果、分享产业前沿动态、汇聚产业创新人才、促进技术交流合作、推动产业生态构建，进一步促进半导体与集成电路创新链产业链供应链的深度融合，助力我国半导体与集成电路产业高质量发展。

To provide more semiconductor and IC enterprises with an international platform to display products, promote trade negotiation, deepen technical exchange and cooperation. Under the guidance of the competent authorities, Golden Group together with relevant administrative units, will hold the "Hangzhou International Semiconductor and Integrated Circuit Industry Innovation Exhibition 2026" from May 14 to 16, 2026 at the Hangzhou Grand Convention and Exhibition Center. With a total planned area of 30,000 square meters, the exhibition takes "Connecting the Chip Ecosystem, Empower the Future with Intelligence" as its theme. The exhibits covers a wide range of products and technologies, including equipment and components, semiconductor materials, EDA & IP, IC design, manufacturing, packaging and testing, semiconductor services, as well as chip application products and technologies. It will bring together cutting-edge technologies and frontier products from the global semiconductor and integrated circuit industry, showcasing the full spectrum of innovation in the sector from chip design to integrated circuit solutions. Combined with exhibition and forums, the event strives to comprehensively showcase the innovative strength and development achievements of China's semiconductor and IC industry particularly in the Yangtze River Delta region from multiple perspectives. It aims to share cutting-edge industry trends, gather together innovative talent, promote technological exchange and collaboration, foster the construction of an industrial ecosystem, and further drive the deep integration of the innovation, industrial and supply chains, which contributed to the high-quality development of China's semiconductor and IC industry.

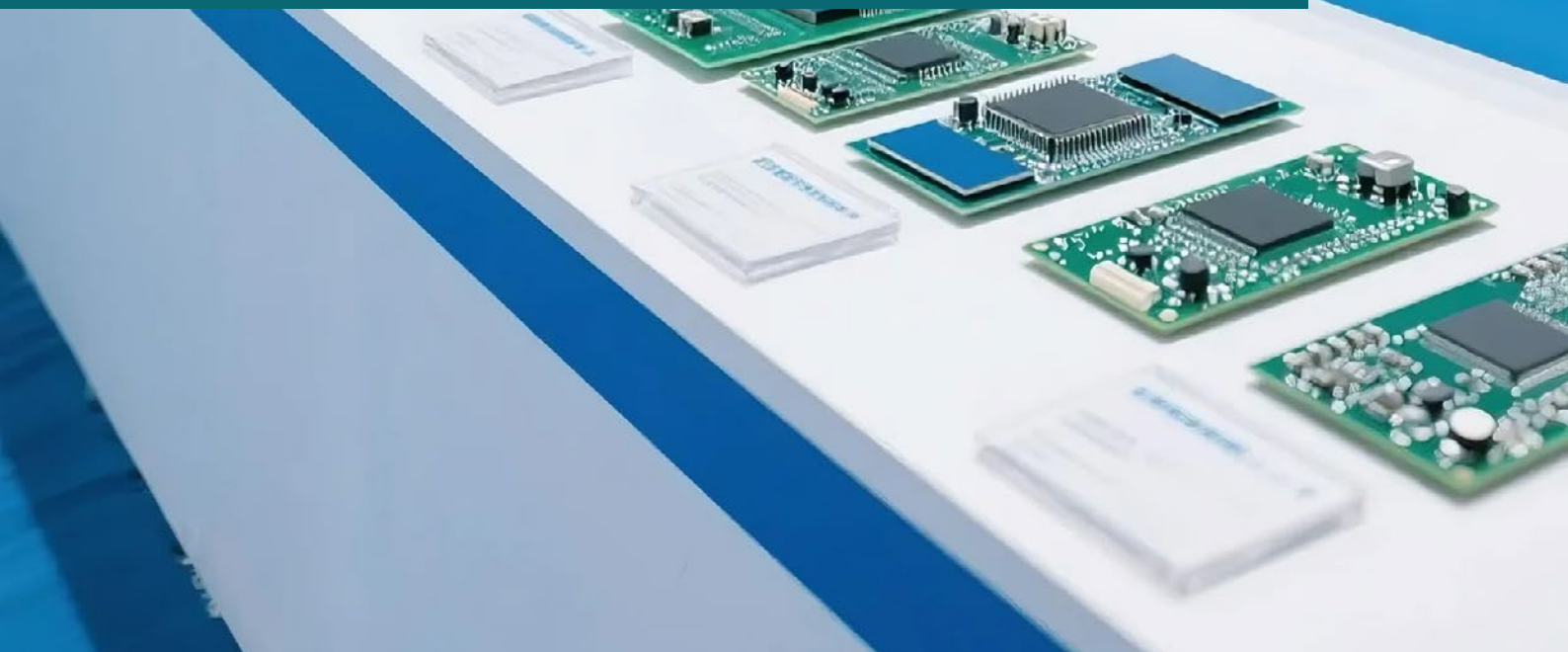
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## 同期活动 CONCURRENT ACTIVITIES

展会同期将举办半导体与集成电路产业发展高峰论坛、技术交流会、投融资对接会、产品首发首秀等多场专业活动，集聚顶尖专家、企业高管与投资机构，深度探讨全球半导体和集成电路发展趋势与关键应用场景。期间，多场半导体全产业链与具身智能、人工智能、物联网、仪器仪表、新能源汽车、网络通信、消费电子等领域的供需对接会将作为展会的最大的亮点，对接会以采购商与参展商对一面对面交流形式进行，通过交流对接完成产品细节的交流与信息的收集，旨在推动产业链上下游企业之间的精准商务合作。

During the exhibition, multiple professional events will be held, including the Semiconductor and Integrated Circuit Industry Development Summit, Technology Exchange Meetings, Investment and Financing Matchmaking Meetings, Product Launches. It will bring together top experts, corporate executives, and investment institutions to engage in in-depth discussions on development trends and key application scenarios of global semiconductor and integrated circuit. A series of supply-demand matchmaking meetings covering a wide range of fields, including the entire semiconductor industry chain, embodied AI, artificial intelligence, IoT, instrumentation, new energy vehicles, network communications, and consumer electronics, serving as a major highlight of the exhibition. Meanwhile, the matchmaking meetings will take the form of face-to-face interactions between buyers and exhibitors to discuss product details and gather information, aiming to facilitate precise business cooperation among upstream and downstream enterprises in the industry chain.





## 展品大类 MAJOR EXHIBITS

**IC设计:** IC设计 (模拟和功率芯片、AI算力芯片、存储芯片、汽车电子芯片、智能家电芯片、人工智能芯片、ASIC芯片、传感器芯片、光电芯片、生物芯片、类脑芯片、量子芯片) ;

IC Design: IC design (analog and power chips, ai computing chips, memory chips, automotive electronics chips, smart home appliance chips, AI chips, asic chips, sensor chips, photonic chips, biochips, neuromorphic chips, quantum chips);

**IC制造:** 晶圆制造、分立器件、光电器件、传感器产品;

IC Manufacturing: Wafer fabrication, discrete devices, optoelectronic devices, sensor products;

**IC封装及测试:** DIP、SOP、QFP、SIP、BGA等传统封装; 倒装、晶圆级封装、2.5D/3D先进封装(TSV及TGV)、Chiplet等先进封装; IC前后端测试服务;

IC Packaging and Testing: Traditional packaging (DIP, SOP, QFP, SIP, BGA); advanced packaging (flip-chip, wafer-level packaging, 2.5d/3d packaging with tsv and tgv, chiplet technology); ic testing services (front-end and back-end)

**EDA&IP;**

TSICE

## 展品大类

## MAJOR EXHIBITS

**半导体设备及零部件：**晶圆加工过程中所需的各种精密设备、半导体封装设备、测试设备；密封圈、精密轴承、金属零部件、Valve阀、硅/SiC件、Robots、石英件、过滤器、射频电源、陶瓷件、ESC静电吸盘、压力Gauge、泵、MFC流量计、步进马达、运动控制、伺服电机、直线模组、无尘拖链、封装模具、制冷设备、感应加热器等半导体零部件；  
Semiconductor Equipment and Components: Precision equipment for wafer fabrication, semiconductor packaging systems, and test equipment; essential components including sealing rings, precision bearings, metal components, valves, silicon/SiC parts, robots, quartz components, filters, RF power supplies, ceramic components, electrostatic chucks (ESCs), pressure gauges, pumps, mass flow controllers (MFCs), stepper motors, motion control systems, servo motors, linear modules, cleanroom cable carriers, packaging molds, refrigeration equipment, induction heaters, and other critical semiconductor parts;

**半导体材料：**单晶硅、硅片等硅基材料；抛光垫、掩膜版、溅射靶材、光刻胶、薄膜沉积材料、前驱体材料、特种气体、抛光液、湿电子化学品等工艺辅助材料；陶瓷封装材料、键合丝、引线框架、封装基板、塑封材料、高性能塑料等封装材料等；  
Semiconductor Materials: Silicon-based materials including monocrystalline silicon, silicon wafers; process auxiliary materials including polishing pads, photomasks, sputtering targets, photoresists, thin-film deposition materials, precursor materials, specialty gases, polishing slurries, wet electronic chemicals; packaging materials including ceramic packaging materials, bonding wires, lead frames, packaging substrates, molding compounds, high-performance plastics;

**化合物半导体材料及产品：**化合物半导体（如磷化铟、碳化硅、氮化镓、氧化镓等）衬底及外延片材料生产企业及其器件、模组产品；  
Compound Semiconductor Materials and Products: Enterprises specializing in compound semiconductor substrates and epitaxial wafers (e.g., indium phosphide, silicon carbide, gallium nitride, and gallium oxide), along with related devices and module products;

**下游芯片应用：**物联网、人工智能、智能网联汽车、健康医疗、具身智能、消费电子、网络通信、仪器仪表等产品；  
Downstream Chip Applications: The Internet of Things (IoT), AI, intelligent connected vehicles (ICV), healthcare, embodied ai, consumer electronics, network communications, and instrumentation;

**配套设施与服务：**各地芯火平台、半导体协会、产业联盟、半导体研究院、中试产线及高校、投融资机构、环保企业、电子类建筑施工企业、一般商业服务/咨询机构、销售、标准化制定及物流冷链等支撑服务企业。  
Supporting Facilities and Services: Xinhua platform, semiconductor associations, industry alliances, semiconductor research institutes, pilot production lines and universities, investment and financing institutions, environmental protection companies, electronic construction enterprises, general business services/consulting firms, sales organizations, standards development bodies, and logistics and cold chain enterprises.



**TSICE**

## 展区设置 EXHIBITION AREAS

1、IC设计	IC Design Pavilion
2、IC制造	IC Manufacturing Pavilion
3、IC封装及测试	IC Packaging and Testing Pavilio
4、EDA&IP	EDA&IP Pavilion
5、半导体设备及零部件	Semiconductor Equipment and Components Pavilion
6、半导体材料	Semiconductor Materials Pavilion
7、化合物半导体材料及产品	Compound Semiconductors Materials and Products Pavilion
8、下游芯片应用	Chip Applications Pavilion
9、配套设施与服务	Supporting Facilities and Services Pavilion

聚焦“高端芯”与“国产替代”的最新突破，打造行业最前沿的技术展示平台。

Focusing on the latest breakthroughs in "high-end chips" and "domestic substitution," the event strives to provide a cutting-edge platform to showcase industry-leading technologies.



## 参展费用 PARTICIPATION FEES

### ★ 标准展位:

A: 国内企业: 标准展位16800.00/展期 (RMB) 3m×3m

B: 国外企业: 标准展位4800.00/展期 (USD) 3m×3m

展位包括: 三面白色壁板、中(英)文楣牌制作、咨询桌一张、折椅二把、地毯满铺、展位照明、220V/5A电源插座一个、废纸篓一个。)

### ★ 室内光地:

A: 国内企业: 1600 (RMB) /平方米

B: 国外企业: 480 (USD) /平方米

注: (最少36平方米起租) “光地” 只提供参展面积, 不包括展架、展具、地毯、电源等。

### International Standard Booths:

For overseas enterprises: USD 4800.00/Expo; 3m×3m

Each standard booth consists of 3-sided white wallboards, Chinese& English fascia board, 1 consultation desk, 2 folding chairs, fully-floored carpet, booth lighting system, 1 power socket 220V/5A, and a waste basket.

### Indoor Raw Space:

For overseas enterprises: USD 480.00/Sq.m.

Note: The raw space (minimum 36 sq.m.) only supplies a show space excluding stand frames, show equipment, carpet and power supply, etc.



## 观众组织 TARGET AUDIENCES

本次展会将全力邀请全球半导体、集成电路、电子电力、电子制造、显示制造以及汽车、航空航天、医疗卫生、信息通信、消费电子等领域专业人士齐聚杭州，共探前沿科技，共商合作大计，携手解码产业新生态，合力共筑开放、协同、韧性的全球半导体与集成电路产业“芯”未来。

It will attract domestic and foreign professionals from semiconductors, IC, electronic power, electronics manufacturing, display manufacturing, as well as automotive, aerospace, healthcare, information and communications, and consumer electronics industry to participate in the exhibition. The event provides an efficient platform for participants to explore cutting-edge technologies, discuss collaborative strategies, jointly decode the new industrial ecosystem, and work together to build an open, collaborative, and resilient core future for the global semiconductor and IC industry.

SICE

## 预定展位 Booth Reservation

请立即预定“SICE 2026”展位，越早预留位置越佳，争取最大曝光率，领先竞争对手，开拓无限商机。

Your timely reservation will allow us to preassign exhibit space. Requests for exhibit space will be accepted on a “first come, first served” basis.

如欲预订“SICE 2026”采购交易会展位，或了解更多信息，请发电子邮件至[info@goldenexpo.com.cn](mailto:info@goldenexpo.com.cn)。

或通过以下联络方法，预订展位。

To reserve the booth of “SICE 2026” or learn more information, please contact:

电话/ Tel : (86-21) 6439-6190 E-mail: [info@goldenexpo.com.cn](mailto:info@goldenexpo.com.cn)